

ABSTRACT OF THE DISCLOSURE

PASSIVATION LAYER FOR SEMICONDUCTOR DEVICE PACKAGING

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Methods of protecting a surface of a copper layer or a copper bonding pad on a semiconductor device against oxidation. A surface of the layer or bonding pad is cleaned by removing an oxidation layer with a plasma. A polymer layer is formed on the cleaned surface of the layer using a plasma-enhanced deposition process to protect
10 the cleaned surface of the layer against exposure to an oxidizing gas.

FIG. 1



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